

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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# 2SC458, 2SC2308

Silicon NPN Epitaxial

**RENESAS**

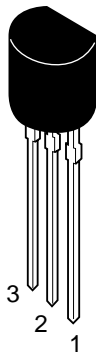
ADE-208-1043 (Z)  
1st. Edition  
Mar. 2001

## Application

- Low frequency amplifier
- Complementary pair with 2SA1029 and 2SA1030

## Outline

TO-92 (1)



1. Emitter
2. Collector
3. Base

## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	2SC458	2SC2308	Unit
Collector to base voltage	$V_{CBO}$	30	55	V
Collector to emitter voltage	$V_{CEO}$	30	50	V
Emitter to base voltage	$V_{EBO}$	5	5	V
Collector current	$I_C$	100	100	mA
Emitter current	$I_E$	-100	-100	mA
Collector power dissipation	$P_C$	200	200	mW
Junction temperature	$T_j$	150	150	°C
Storage temperature	$T_{stg}$	-55 to +150	-55 to +150	°C

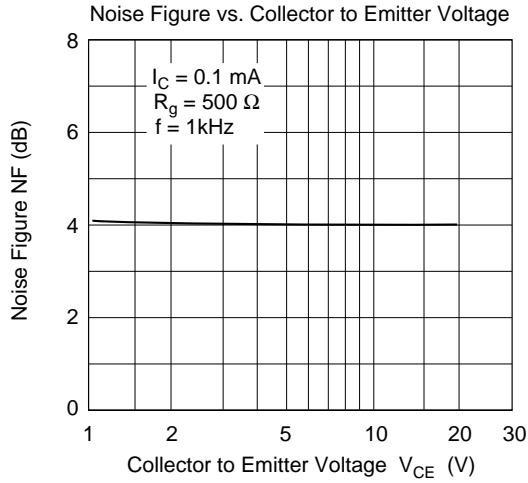
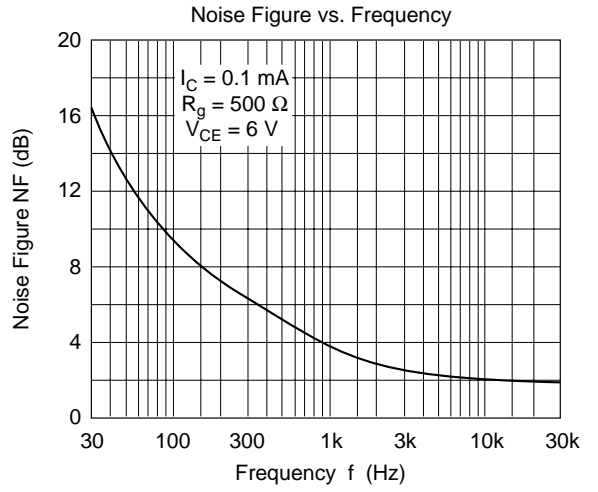
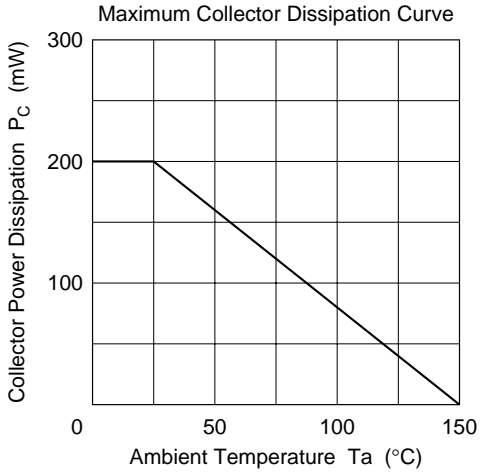
## Electrical Characteristics (Ta = 25°C)

Item	Symbol	2SC458			2SC2308			Unit	Test conditions
		Min	Typ	Max	Min	Typ	Max		
Collector to base breakdown voltage	$V_{(BR)CBO}$	30	—	—	55	—	—	V	$I_C = 10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	30	—	—	50	—	—	V	$I_C = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	—	—	5	—	—	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	$I_{CBO}$	—	—	0.5	—	—	0.5	$\mu A$	$V_{CB} = 18 \text{ V}, I_E = 0$
Emitter cutoff current	$I_{EBO}$	—	—	0.5	—	—	0.5	$\mu A$	$V_{EB} = 2 \text{ V}, I_C = 0$
DC current transfer ratio	$h_{FE}^{*1}$	100	—	500	100	—	320		$V_{CE} = 12 \text{ V}, I_C = 2 \text{ mA}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	0.2	—	—	0.2	V	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$
Base to emitter voltage	$V_{BE}$	—	0.67	0.75	—	0.67	0.75	V	$V_{CE} = 12 \text{ V}, I_C = 2 \text{ mA}$
Gain bandwidth product	$f_T$	—	230	—	—	230	—	MHz	$V_{CE} = 12 \text{ V}, I_C = 2 \text{ mA}$
Collector output capacitance	Cob	—	1.8	3.5	—	1.8	3.5	pF	$V_{CB} = 10 \text{ V}, I_E = 0,$ $f = 1 \text{ MHz}$
Noise figure	NF	—	4	10	—	4	10	dB	$V_{CE} = 6 \text{ V}, I_C = 0.1 \text{ mA},$ $f = 1 \text{ kHz}, R_g = 500 \Omega$
Small signal input impedance	$h_{ie}$	—	16.5	—	—	16.5	—	k $\Omega$	$V_{CE} = 5 \text{ V}, I_C = 0.1 \text{ mA},$ $f = 270 \text{ Hz}$
Small signal voltage feedback ratio	$h_{re}$	—	70	—	—	70	—	$\times 10^{-6}$	
Small signal current transefer ratio	$h_{fe}$	—	130	—	—	130	—		
Small signal output admittance	$h_{oe}$	—	11.0	—	—	11.0	—	$\mu S$	

Note: 1. The 2SC458 and 2SC2308 are grouped by  $h_{FE}$  as follows.

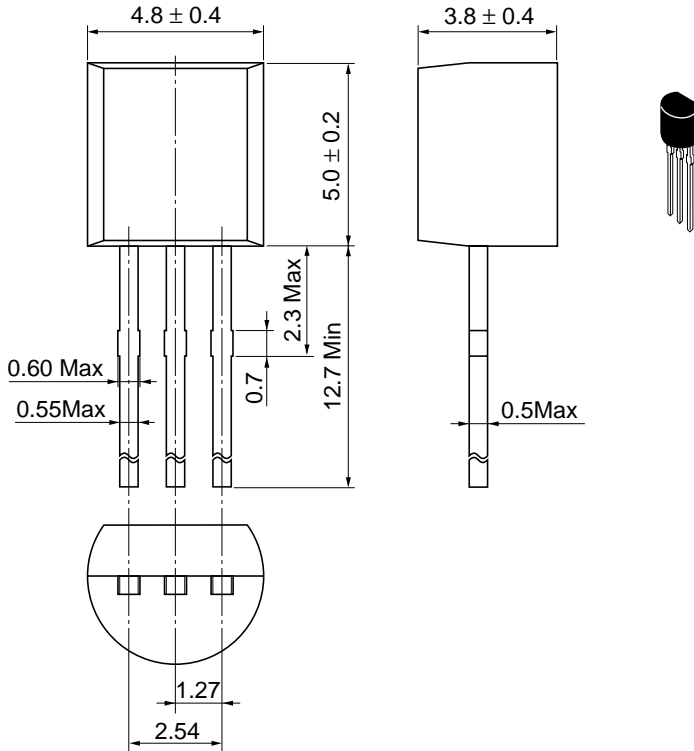
	B	C	D
2SC458	100 to 200	160 to 320	250 to 500
2SC2308	100 to 200	160 to 320	—

See characteristic curves of 2SC458 (LG) and 2SC2310 except for the followings.



Package Dimensions

As of January, 2001  
Unit: mm



Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.25 g

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